



All Issue Details

Project: SPX19432

Member ID: forksand **Name:** Jeff Moe

Order#: 1306986-iRW **Part#:** TRELLIS

Sunnyvale, CA

(800) 763-7503

www.protoexpress.com

IST137024

RESOLVED

Category	PCB CAM & Planning	Issue	Design Issue- Gerber related
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Details Udaya Kumar Sep 6 2019 5:45PM

While performing DFM validation on your order we observed, your data contain 12 slots(11 plated and 1 non-plated) but as per web spec only 3 plated and 7 non-plated slots are allowed. This may require to revise your quote for which our sales team will be in touch with you.

ISSUE POSTS

Jeff Moe Sep 6 2019 6:52PM

Ok, revise quote as needed.

 Azad kalam Sep 6 2019 7:13PM

@Eric Wolheim, we will resolve this issue. Please take care any financial aspects.

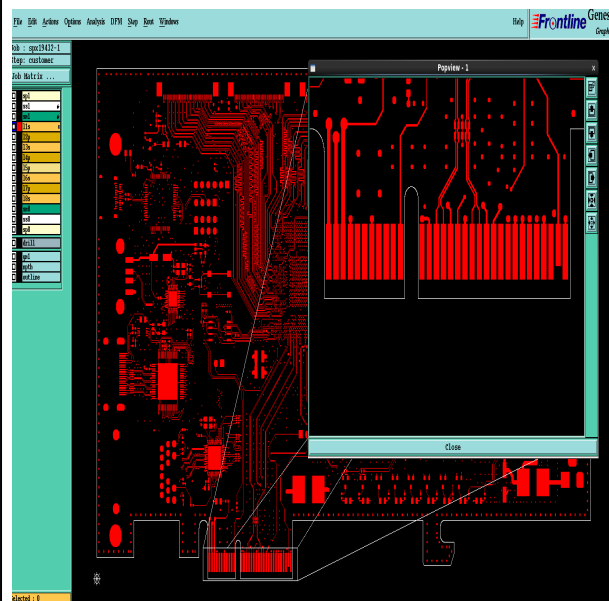
IST137030

RESOLVED

Category	PCB CAM & Planning	Issue	Missing information- Type of Gold/Gold thickness
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Details Udaya Kumar Sep 6 2019 5:45PM

While performing DFM validation, we observed finger like features are present but web Spec calls for gold finger as "None". Please confirm whether you require hard gold plating for the fingers or you want the whole board to be ENIG finish. FYI: In case of hard gold plating requirement for the fingers, we need to revise the quote for which our sales team will be in touch with you.



Screenshot.png

ISSUE POSTS

Jeff Moe Sep 6 2019 6:52PM

No gold plating is required. Whole board ENIG.

IST137041

RESOLVED

Category

PCB CAM & Planning

Issue

Design Issue- Drill related

Details Udaya Kumar Sep 6 2019 5:45PM

While performing DFM validation we observed that, web spec calls for number of holes per board: 120, but gerber data received has 3367 number of holes. Can we proceed as per gerber data? Please confirm.

ISSUE POSTS

Jeff Moe Sep 6 2019 6:51PM

Proceed as per gerber data.

IST137045

RESOLVED

Category

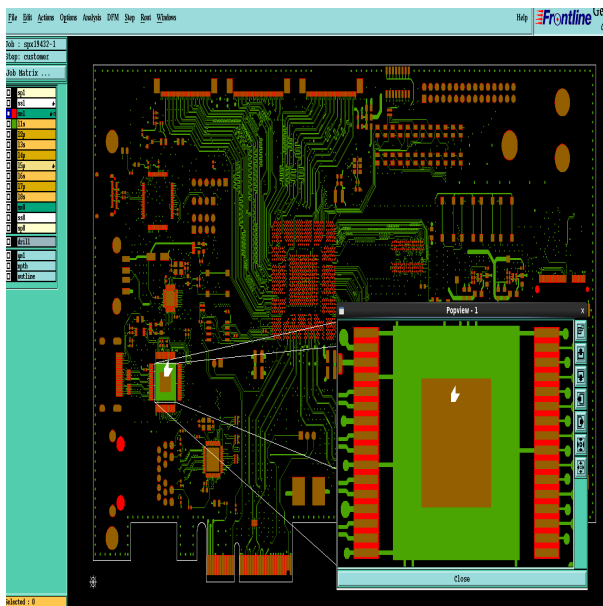
PCB CAM & Planning

Issue

Design Issue- Solder mask related

Details Udaya Kumar Sep 6 2019 5:45PM

While DFM validation, we observed partial mask opening for rectangular pad at one location in top mask layer. Find Enclosed snap shot for your quick reference. Can we provide complete mask opening at this location(Pad size+4Mils) OR would you like us to proceed as is? Please confirm.



top maks.png

ISSUE POSTS

Jeff Moe Sep 6 2019 7:05PM

Provide complete mask opening at this location(Pad size+4Mils).

IST137050

RESOLVED

Category

PCB CAM & Planning

Issue

Other

Details Udaya Kumar Sep 6 2019 5:45PM

While performing DFM validation, we observed finger like features are present but bevel information is not provided. Can we proceed as per standard (15 mils bevel depth with 45 degree angle)? Please confirm.

ISSUE POSTS

Jeff Moe Sep 6 2019 6:53PM

Proceed as per standard.

IST137053

RESOLVED

Category

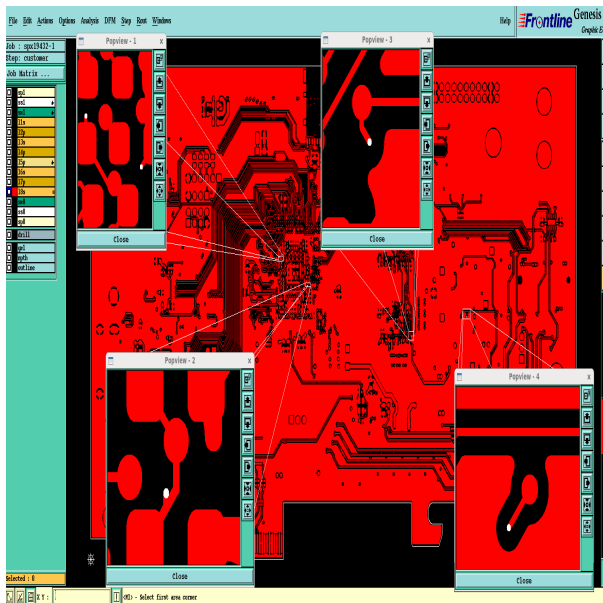
PCB CAM & Planning

Issue

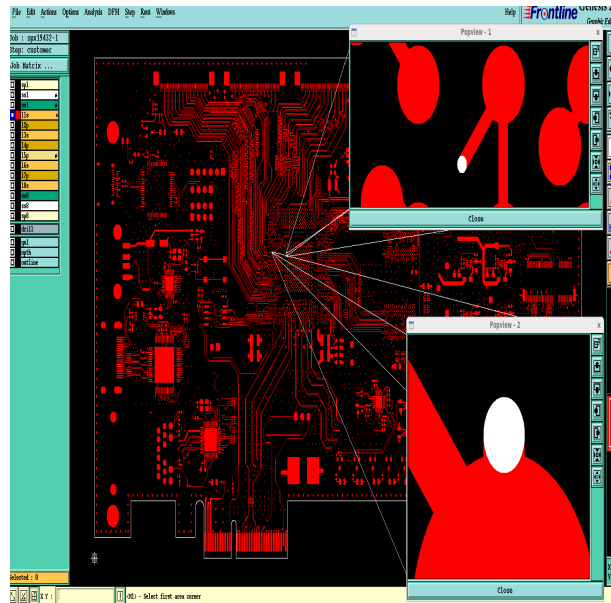
Design Issue- Gerber related

Details Udaya Kumar Sep 6 2019 5:45PM

While performing DFM validation on your order, we observed few un-terminated traces (stubs) in top and bottom layer. Please confirm whether this is by design or else advise. Attached snap shot for your quick reference.



bottom layer.png



top layer.png

ISSUE POSTS

Jeff Moe Sep 6 2019 6:54PM

I don't know...

 Azad kalam Sep 6 2019 7:07PM

Can we proceed as is? Please confirm.

Jeff Moe Sep 6 2019 7:07PM

I was just looking into this. Please proceed as is.

IST137059

RESOLVED

Category

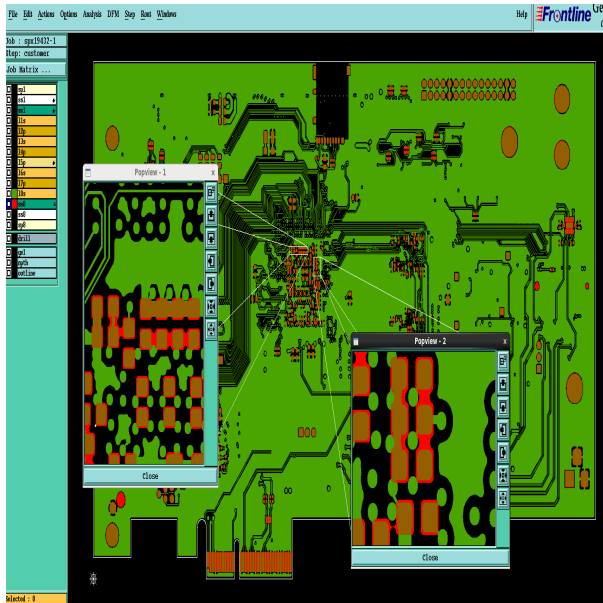
PCB CAM & Planning

Issue

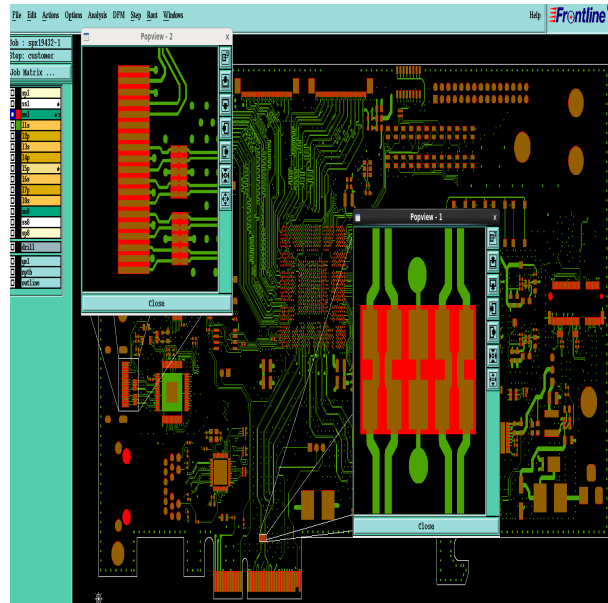
Design Issue- Solder mask related

Details Udaya Kumar Sep 6 2019 5:45PM

While performing DFM validation we observed that, Gang mask opening is provided in both solder mask layer. Find attached snap shot for your quick reference. This job is going to be assembled at our facility and we prefer individual mask opening. Please allow us to remove Gang relief and go ahead with individual mask opening. Please confirm.



bottom mask.png



top mask.png

ISSUE POSTS

Jeff Moe Sep 6 2019 6:50PM

Ok, confirmed.

IST137063

RESOLVED

Category

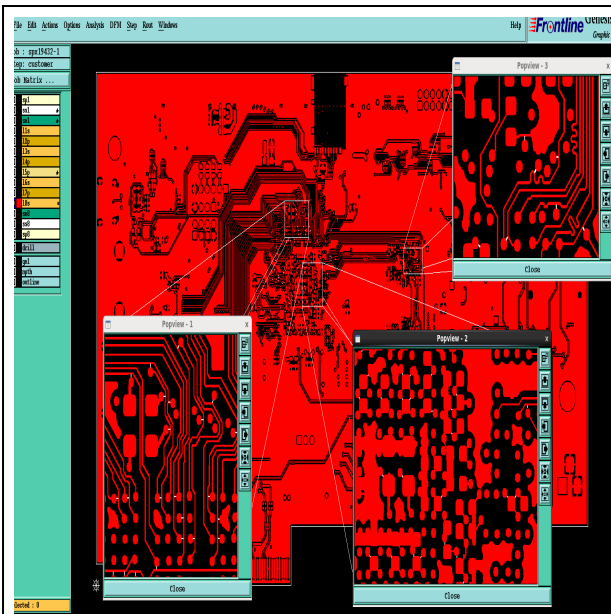
PCB CAM & Planning

Issue

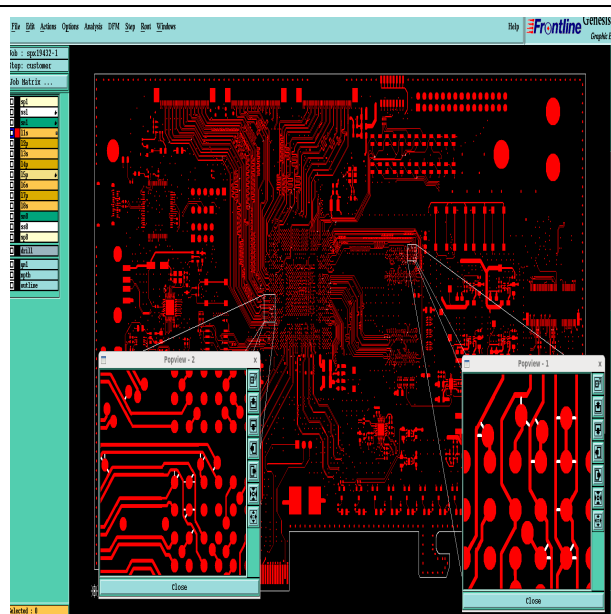
Design Issue- Gerber related

Details Udaya Kumar Sep 6 2019 5:45PM

While performing DFM validation on your order we observed that 3.042 mil spacing on your design (top and bottom layer) but web spec calls 4 mil spacing. Also less than 4Mils spacing is not qualified for Web orders. This may required custom quote for which our sales team will get in touch with you.



bottom layer.png



top layer.png

ISSUE POSTS

Jeff Moe Sep 6 2019 6:49PM

Ok, please proceed with custom quote.

 Azad kalam Sep 6 2019 7:19PM

This issue requires to revise the quote for which our sales team will get in touch with you.

 Darren Cruz Sep 9 2019 10:29AM

Hi Jeff, per your account manager, the additional cost will be \$500. Please confirm asap.

Jeff Moe Sep 9 2019 10:30AM

Confirmed.

IST137082

RESOLVED

Category	Assembly Engineering	Issue	Assembly- XY data missing
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Details Jayson Fernandes Sep 6 2019 7:19PM

Pick-and-place file is missing in your provided set of gerber files. Please provide us the pick-and-place file containing reference designators, assembly side, X location, Y location and rotation information so that we can validate your gerber files for assembly. Until then, your order is kept On-Hold for DFA checks.

ISSUE POSTS

Jeff Moe Sep 6 2019 7:22PM

See attached.



ecp5_mainboard-bottom.pos



ecp5_mainboard-top.pos

Jeff Moe Sep 6 2019 7:22PM

Note these are the same as .txt or .asc files.

Jeff Moe Sep 6 2019 7:23PM

Also, I can upload the whole "ecp5_mainboard.kicad_pcb" file, which should have everything, if you can read that.

Jeff Moe Sep 6 2019 7:33PM

I've also uploaded the .kicad_pcb file, in case you can read that. If not the above .pos files should do. I can also export the .pos files in .csv, if you prefer.



ecp5_mainboard.kicad_pcb

Jayson Fernandes Sep 6 2019 7:40PM

We will proceed with the .pos files only.

Jayson Fernandes Sep 6 2019 7:41PM

Thank you, we will let you know if we find any issues for DFA checks.

IST137090

RESOLVED

Category

Assembly Engineering

Issue

Assembly- IBOM issue resolution not complete

Details Jayson Fernandes Sep 6 2019 8:01PM

As per information received to us during online quotation, your boards are to be cleaned after assembly. But the below components are Non-Washable. Please advise if we must follow clean process or proceed with clean such that the non-washable components will be soldered manually after assembly. SW1 (Line item# 73 MPN: CHP-081TA)

ISSUE POSTS

Jeff Moe Sep 6 2019 9:02PM

Proceed with clean such that the non-washable components will be soldered manually after assembly.

Category

Assembly Engineering

Issue

Assembly- Other

Details Bireshwar Basuvraj Sep 6 2019 9:57PM

For the DFA checks shows most of the components are missing in XY data, but present in BOM. Please find the attached report for your Reference. Kindly review and provide us the updated XY data, hence we can proceed with your jobs. Until then, your order is kept On-Hold for DFA checks.



XY Report.xlsx

ISSUE POSTS

Jeff Moe Sep 7 2019 8:15AM

See attached.



ecp5_mainboard-all-pos.csv

Sagar Sawal Sep 9 2019 10:01AM

We will verify your provided file.

Bireshwar Basuvraj Sep 9 2019 11:14AM

Below mentioned components again missing in updated XY data. Kindly review and advise.

J1, J3, J4, J8, J14, J9, JP1, P1, P4.

Ref ID	Description	XY Che	Doubled Che	Packag	Package Che
J1	PJ-037A	NO XY	OK		#N/A
J3	471510001	NO XY	OK		#N/A
J4	292303-7	NO XY	OK		#N/A
J8	9774025151R	NO XY	OK		#N/A
J14	9774025151R	NO XY	OK		#N/A
J9	PPPC152LJBN-RC	NO XY	OK		#N/A
JP1	61300311121	NO XY	OK		#N/A
P1	2199230-4	NO XY	OK		#N/A
P4	JK0654219NL	NO XY	OK		#N/A

Capture.JPG

Jeff Moe Sep 9 2019 11:17AM

I see those parts are all listed as "Pads THT" in the bom, so apparently may r

require manual placement.

 Jayson Fernandes Sep 9 2019 11:35AM

We will proceed with the provided pick-and-place file provided above. These above mentioned components will be verified according to its relevant reference designator's on silkscreen. Let you know if any issues found.

IST137180

RESOLVED

Category

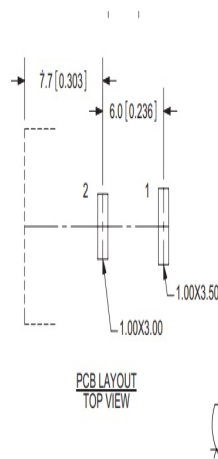
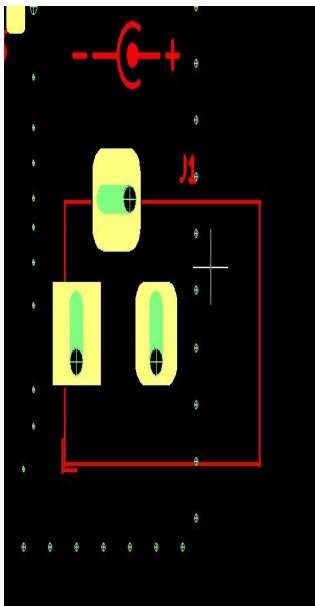
Assembly Engineering

Issue

Assembly- Foot Print mismatch

Details Bireshwar Basuvraj Sep 9 2019 12:52PM

DFA checks of your files show a footprint mismatch of components J1 (Line Item# 29) [MPN: PJ-037A] in GERBER files w.r.t. mechanical dimensions as per datasheet. As shown in image, Gerber footprint is not matching with recommended land pattern. Kindly provide an alternate part# for this or advise if we need to make component DNI.



j1.JPG

ISSUE POSTS

Jeff Moe Sep 9 2019 12:57PM

PerIST137106 that is going to be manually placed.

 Jayson Fernandes Sep 9 2019 2:47PM

We will place it on available footprint.

IST137182

RESOLVED

Category

Assembly Engineering

Issue

Assembly- BOM components missing in Gerber and placement files

Details Bireshwar Basuvraj Sep 9 2019 12:52PM

DFA checks of your files show that components mentioned below are present in BOM but missing in Gerber files

and placement files. Kindly review and advice assembly location. J8,J14 (Line Item# 35) [MPN: 9774025151R]

ISSUE POSTS

Jeff Moe Sep 9 2019 12:58PM

PerIST137106 those are to be manually placed.

Jeff Moe Sep 9 2019 1:39PM

Reviewing further, they standoffs that don't need to be installed. Do not place J8 J14.



Jayson Fernandes Sep 9 2019 2:56PM

Per your advise, we will DNI the components J8,J14 and ship them to you along with the boards.

IST137183

RESOLVED

Category

Assembly Engineering

Issue

Assembly-Mechanical/Package dimension details needed

Details Bireshwar Basuvraj Sep 9 2019 12:52PM

For the DFA checks, we need you to provide the mechanical dimensional datasheet (Footprint information) of components mentioned below for footprint verification as we could not find one. U15 (Line Item# 79) [MPN: LFE5UM5G-85F-8BG756C] This datasheet must contain the mechanical dimensions of the component such as pitch, length, width etc.

ISSUE POSTS

Jeff Moe Sep 9 2019 1:02PM

See attached datasheet from Lattice.



FPGA-DS-02012-2-1-ECP5-ECP5G-Family-Data-Sheet.pdf

IST137275

RESOLVED

Category

PCB CAM & Planning

Issue

Data Discrepancy-Manufacturing specs

Details Kumar Periasamy Sep 9 2019 5:53PM

@Jeff --After running DRC on the design, we have observed an issue. One of the documents received by our assembly team calls for bevelling of boards at the bottom edge of the board. As discussed with you over phone, there is no beveling required as copper is very near to the board edge in layer 2,7 & 8 and beveled edges will expose the copper. As you don't want the copper to be pulled back, you have agreed to without beveling. Please reply for the confirmation.

ISSUE POSTS

Jeff Moe Sep 9 2019 5:53PM

Confirmed, no beveling required.

IST137318

RESOLVED

Category

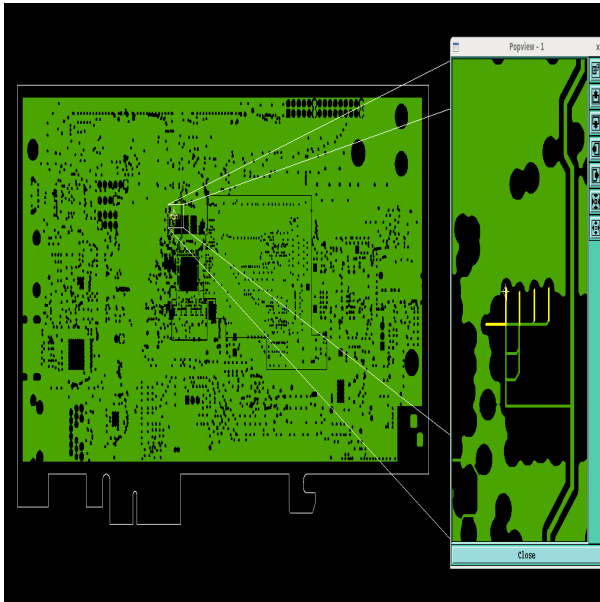
PCB CAM & Planning

Issue

Data Discrepancy- Gerber related

Details Ismail K Sep 9 2019 10:37PM

While performing DRC on your order, we observed stubs(Un-terminated traces) on inner layer4 at 5 locations. Please confirm can we proceed as is or else advise. Screen shot attached for your reference



160832-stubs on layer4.png

ISSUE POSTS

Jeff Moe Sep 10 2019 7:42AM

Proceed.

IST138178

RESOLVED

Category

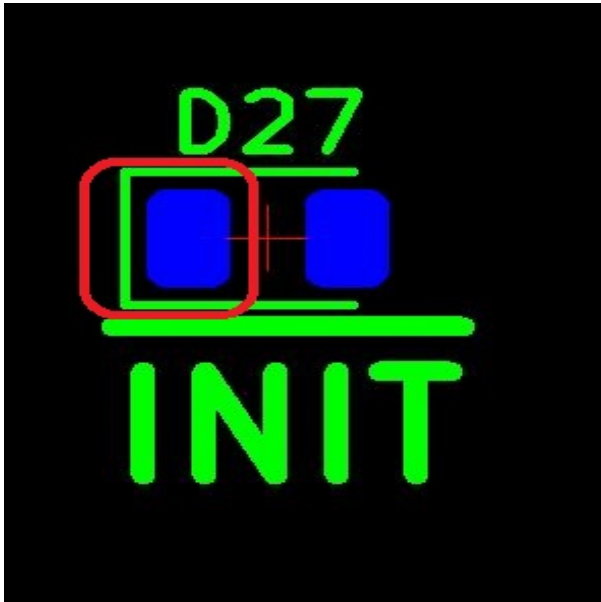
Assembly Engineering

Issue

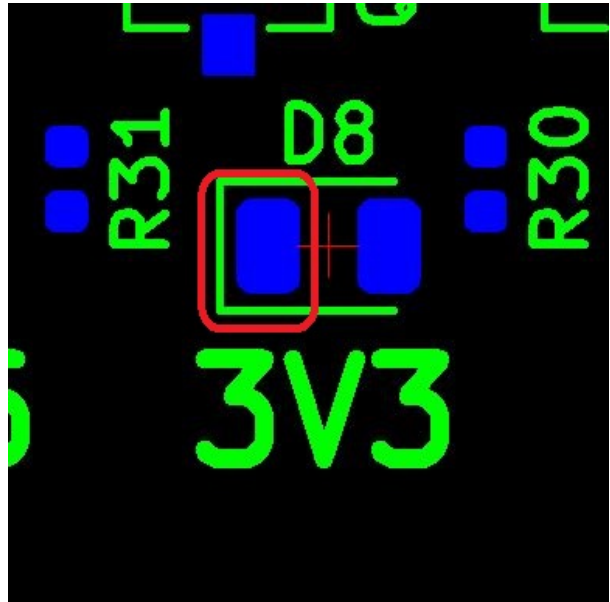
Assembly- Cathode Mark confirmation needed

Details Valerious Travasso Sep 16 2019 10:47AM

We need you to advise if the marked pad of components mentioned below is cathode: D27 (Line Item# 22) [MPN: LH R974-LP-1] D8,D2,D26,D4,D5,D6,D7,D9,D10,D11,D12,D13 (Line Item# 24) [MPN: LG R971-KN-1]



D27.jpg



D8.jpg

ISSUE POSTS

Jeff Moe Sep 16 2019 10:54AM

Sent to engineers for review.

Jeff Moe Sep 16 2019 1:11PM

D8, D2, D26, D4, D5, D6, D7, D9, D10, D11, D12, D13 cathode is on left.

Jeff Moe Sep 16 2019 1:26PM

D27 Cathode is on the left, as circled.

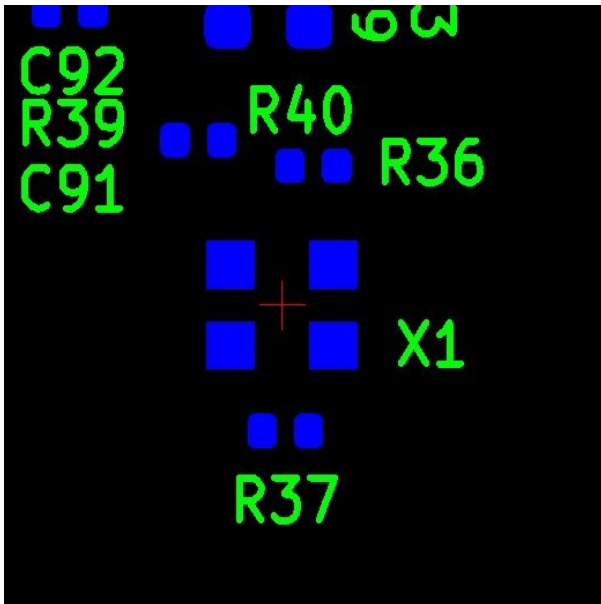
IST138179

RESOLVED

Category	Assembly Engineering	Issue	Assembly- No Polarity marking
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Details Valerious Travasso Sep 16 2019 10:47AM

We need you to advise for the PIN1 marking for below mentioned components as it is missing in silkscreen layer. X1 (Line Item# 95) [MPN: ASE-12.000MHZ-LC-T]



X1.jpg

ISSUE POSTS

Jeff Moe Sep 16 2019 10:54AM

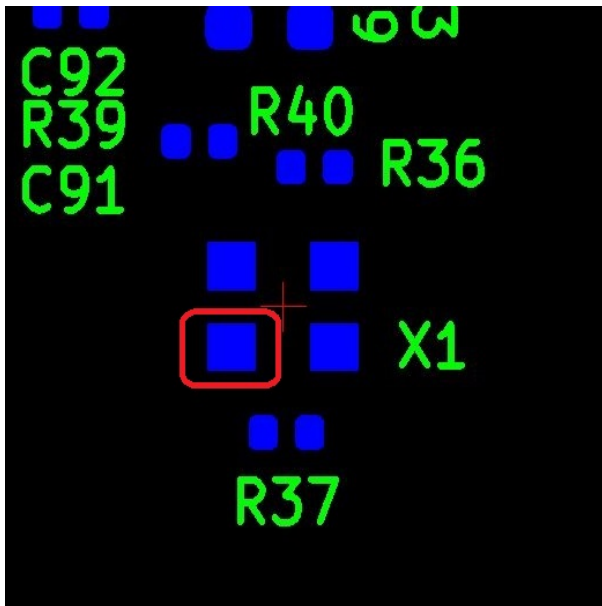
Sent to engineers for review.

Jeff Moe Sep 16 2019 11:55AM

X1 Pin 1 is bottom left in your image.

 Valerious Travasso Sep 16 2019 1:05PM

As per your reply we have considered below marked pad as pin1.



X1.jpg

IST138180

RESOLVED

Category

Assembly Engineering

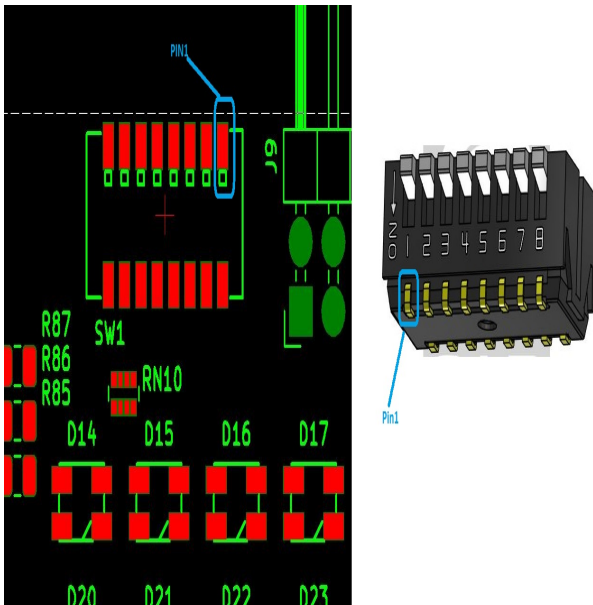
Issue

Assembly- Mounting
orientation confirmation

needed

Details Valerious Travasso Sep 16 2019 10:47AM

For the DFA checks, we need you to advise if the marked pad of components mentioned below is pin-1: SW1 (Line Item# 73) [MPN: CHP-081TA]



Capture.JPG

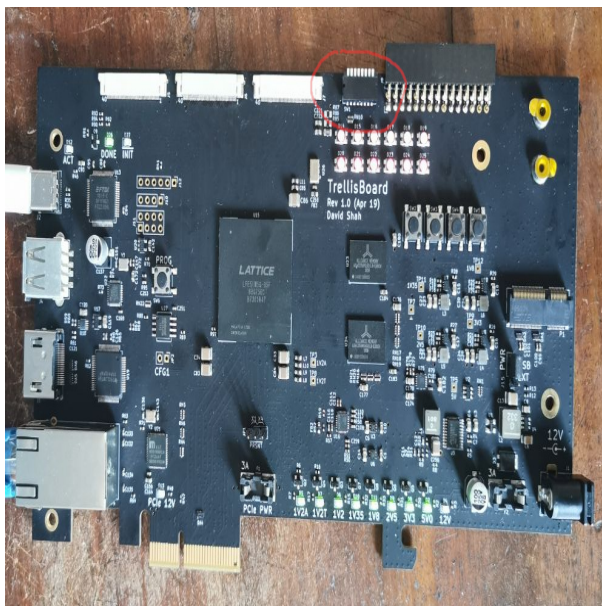
ISSUE POSTS

Jeff Moe Sep 16 2019 10:54AM

Sent to engineers for review.

Jeff Moe Sep 16 2019 11:39AM

See attached photo of board. It looks like you have pin one in opposite corner in your diagram.



trellis-SW1.jpg

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